

Title (en)

ACID BATH FOR COPPER PLATING, AND A PROCESS USING A BATH OF THIS TYPE FOR THIS PURPOSE.

Title (de)

SAURES BAD ZUR GALVANISCHEN ABSCHIEDUNG VON KUPFERÜBERZÜGEN UND VERFAHREN UNTER VERWENDUNG DIESER KOMBINATION.

Title (fr)

BAIN ACIDE POUR LE DEPOT ELECTROLYTIQUE DE COUCHES DE CUIVRE ET PROCEDE AVEC UTILISATION DE CETTE COMBINAISON.

Publication

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Application

EP 91917496 A 19911011

Priority

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- DE 9100811 W 19911011

Abstract (en)

[origin: WO9207116A1] The invention concerns an aqueous acid copper-electroplating bath and the use of the bath for the electrolytic deposition of copper.

IPC 1-7

C25D 3/38

IPC 8 full level

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CPC (source: EP)

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WO 9207116 A1 19920430; AT E115651 T1 19941215; CA 2093924 A1 19920414; CA 2093924 C 20020205; DE 4032864 A1 19920416; DE 4032864 C2 19930107; DE 59103933 D1 19950126; EP 0554275 A1 19930811; EP 0554275 B1 19941214; ES 2066477 T3 19950301; JP H06501986 A 19940303

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